



## **ERS displays its innovative product spectrum at PSECE 2013 trade fair**

MUNICH, May 28, 2013 - ERS electronic GmbH, the innovation leader in the market of thermal wafer chucks in semiconductor production, will show its spectrum of wafer chuck systems at the Philippine Semiconductor and Electronics Convention and Exhibition (PSECE). In the spotlight of ERS' presence at the event is the innovative ERS AirCool®3 modular chuck system.

During the event, which will take place from June 5 - 7, ERS electronic will speak on thermal testing of semiconductors at the wafer level. This presentation will draw from ERS' 43 years of experience as equipment supplier to the semiconductor industry with an emphasis on hot/cold testing of semiconductors destined for automotive applications. The lecture will cover the advantages and disadvantages of various coolants leading to ERS's decision to concentrate on air as the most reliable, flexible and cost-efficient cooling solution.

ERS will also officially announce that Harald Ibele, currently General Manager of ERS America, will lead ERS business in Asia focused on the Philippines in Manila. Manila was the logical choice for ERS based on the existing sales base at the test floors of several semiconductor manufacturers and the centralized location in the Asian high-tech region. "We are experiencing the strongest demand growth in Asia. Therefore it was the logical step to expand our presence here," commented ERS General Manager Klemens Reitingner.

By assuming the task of managing ERS' Asian activities, Harald Ibele takes on a new challenge after having successfully launched the company's U.S. business. A seasoned expert in the field of wafer-level semiconductor testing, Ibele grew ERS' U.S. business to its current size.

ERS can be found at booth 123 at the PSECE fairground in the SMX Convention Center, Manila. The lecture will take place on stage 1, hall 1.

For more information visit [www.ers-gmbh.com](http://www.ers-gmbh.com)

### **About ERS electronic GmbH:**

ERS electronic GmbH, located near Munich, is in its 40th year of supplying the most innovative thermal test solutions to the semiconductor industry. The most famous products are its fast-ramping and precise low-noise thermal chuck systems (-65°C to +500°C) for analytical, parametric and wafer sort probing up to 300mm. ERS also designs and builds stand-alone thermal-forcing systems and custom production tools for special applications. ERS invented the AirCool®, AirCool® plus and PowerSense® thermal chuck systems that have been fully integrated into all major manual, semi- and fully automatic wafer probers.

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